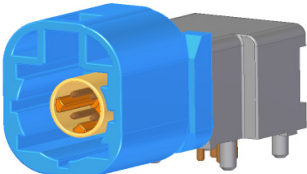


Product Data Sheet / Produkt Datenblatt

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Part Number	5185.HSD.1X10.00Z	Teilenummer
Description	HSD PCB mount angle plug Type	Beschreibung
		
Design according to		Ausführung nach

Electrical characteristics / Elektrische Eigenschaften

		Value/Wert	Unit/Einheit	
		colored value means: still under test target value		
Impedance (MIL-C-39012B)		100 ± 10%	[Ω]	Impedanz (MIL-C-39012B)
Operating frequency up to		6	[GHz]	Betriebsfrequenz bis zu
Return loss	DC - 0,5GHz	≥ 40	[dB]	Rückflusssdämpfung
	DC - 1GHz	≥ 27	[dB]	
	DC - 2GHz	≥ 22	[dB]	
	DC - 6GHz	≥ 10	[dB]	
Insertion loss	DC - 1GHz	≤ 0,1	[dB]	Einfügedämpfung
Nearend crosstalk	DC - 2GHz	≥ 37	[dB]	Übersprechen nahes Ende
	DC - 6GHz	≥ 24	[dB]	
Farend crosstalk	DC - 2GHz	≥ 40	[dB]	Übersprechen fernes Ende
	DC - 6GHz	≥ 30	[dB]	
Skew (between wire pairs)		≤ 5	[psec]	Laufzeitdifferenz zwisch. Adernpaaren
RF Leakage	DC - 1GHz	≥ 75	[dB]	Schirmdämpfung
	DC - 2GHz	≥ 65	[dB]	
Insulation resistance		≥ 1x 10 ³	[MΩ]	Isolationswiderstand
Contact resistance				Kontakt-Widerstand
Centre contact		≤ 10	[mΩ]	Innenkontakt
Outer contact		≤ 7,5	[mΩ]	Außenkontakt
Contact current max. (DC)		≤ 1,5	[A] DC	Kontakt-Strombelastbarkeit max (DC)
Operating voltage		max. 100	[V] DC	Betriebsspannung
Proof voltage		min. 250	[V] eff	Prüfspannung
Contact current max. (DC)		≤ 1,5	[A] DC	Kontakt-Strombelastbarkeit max (DC)

Mechanical characteristics / Mechanische Eigenschaften

		Value/ Wert	Unit/Einheit	
Engagement force		≤ 30	[N]	Steckkraft
Separating force		≥ 5	[N]	Ziehkraft
Mating cycles		≥ 25		Steckzyklen
Coding efficiency		≥ 80	[N]	Kodierungseffizienz
Retention force locked system		≥ 110	[N]	Bauteilfestigkeit

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Date/Approved:

Revision

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Part Number	5185.HSD.1X10.00Z	Teilenummer
Description	HSD PCB mount angle plug Type	Beschreibung

Material & plating / Material & Oberfläche

	RoHS (2002/95/EC) conform	
	Material/Material	Plating/Oberflächen
Outer contact	Brass	Ni 3-6µm
Centre contact - contact outside	Brass	Ni. + sel. Au min. 0,15µm
Centre contact - pcb side		Ni. + sel. Tin plated
Plastic housing	PA 10T/X (UL94-HB)	
Housing	Zink alloy	Cu+Ni+Tin
Insulator	LCP (UL94-V0)	
Cap	Zink alloy	Cu+Ni

Environmental influences:	Umwelteinflüsse	
Operating temperature range	-40°C up to +105°C	Betriebstemperaturbereich
Thermal shock	DIN IEC 60068-2-14 Test NA	Temperaturwechsel
Temperature and Humidity	USCAR 2-4 5.6.2	Temperatur und Luftfeuchtigkeit
Vibration (Random)	DIN IEC 60068-2-64	Vibration (Rauschen)
Mechanical Shock	DIN IEC 60068-2-27	Mechanischer Schock
High-Temp. Exposure	DIN IEC 60068-2-2	Trockene Wärme
Solder profile	IEC 60068-2-58 Group 3&4	Lötprofil

Notes:	Aufzeichnungen
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While the information has been carefully compiled to the best of our knowledge, nothing is intended as representation or warranty on our part and no statement herein shall be construed as recommendation to infringe existing patents. In the effort to improve our products, we reserve the right to make changes judged to be necessary.

Update History

Rev.	Date	Signature	Alteration	Approved
				Formblatt-Nr.: Form-TK-013ab
				Rev. 04
				Released 17. Apr 14

Date/Generated: 16.12.15 / MF

Revision

Date/Approved:

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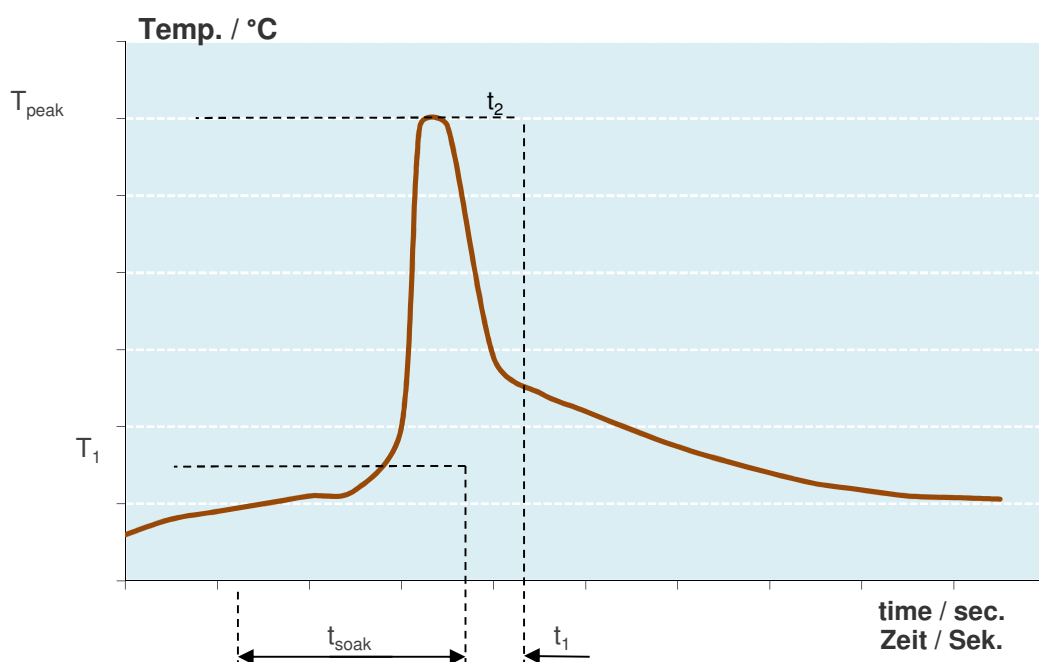
Part Number	5185.HSD.1X10.00Z	Teilenummer
Description	HSD PCB mount angle plug Type	Beschreibung

Soldering process / Lötprozess

Soldering methode/
Lötmethode: THT - Wavebath solderability / Wellenlötbad

Recommended wave soldering profile /
Empfohlenes Lötprofil (Wellenbad):

Parameter	Reference	Specification
Temperature gradient in preheating / Temperaturgradienten in Vorwärmen		2°C/s max.
Soak time / Setzzeit	t_{soak}	< 30 seconds
Preheat temperature/Temperatur vorheizen	T_1	< 100° (-5/+5)°C
Temperature gradient time/ Temperaturgefälle (Zeit)	t_1	5-6 second
Soldering time / Lötdauer	t_2	10 Seconds max.
Peak temperature / Spitzentemperatur	T_{peak}	300°C max.
Temperature gradient in cooling/ Temperaturgradienten in Kühlung		6°C/Seconds max.



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Part Number	5185.HSD.1X10.00Z	Teilenummer
Description	HSD PCB mount angle plug Type	Beschreibung

Soldering process / Lötprozess

Soldering methode /
Lötmethode: THR / Reflow

Recommended reflow soldering profil /
Empfohlenes reflow Lötprofil:

Parameter	Reference	Specification
Max. Temperature (lead free soldering) Max. Temperatur (bleifreies Löten)	C°	260°

